

Y-206BSRY-206BSRP

Black, Low CTE, High modulus Laminate & Prepreg for IC Packages

产品特点:

- 无卤, Tg 200°C (DMA)
- 低膨胀、低收缩
- 高模量(高弹性率)
- 黑色和良好的光遮蔽性能
- 优异的耐热性
- 优异的尺寸稳定性
- 优异的厚度均匀性

应用领域:

CSP、BGA、FC-PKG 等封装用基板。

Key Features:

- Halogen Free and Tg 200°C (DMA)
- Low CTE and low shrinkage
- High modulus
- Black and good light blocking
- Excellent heat resistance
- Excellent dimensional stability
- Excellent uniformity of thickness

Applications:

Substrates for CSP、BGA、FC-PKG etc.

1、General properties

Property	Item	IPC-TM-650	Test Condition	Units	Typical value
热性能 Thermal	玻璃化转变温度 Glass Transition Temperature	2.4.24.4	DMA	°C	200
	X,Y 轴方向膨胀系数 X,Y-CTE	2.4.24.5	TMA	ppm/°C	9~12
	Z 轴方向膨胀系数 Z axis-CTE	2.4.24	TMA, Before TG	ppm/°C	25
			TMA, After TG	ppm/°C	101
			50~260 °C	%	1.7
	288°C 分层时间 T288	2.4.24.1	Clad	min	>60
			Etched	min	>60
	288°C 热冲击 Thermal stress	2.6.8	288°C, solder dip	S	>300
热失重(weight loss 5%) Decomposition temperature	2.4.24.6	TGA	°C	385	
电性能 Electrical	体积电阻 Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	>10 ⁸
	表面电阻 Surface Resistivity	2.5.17.1	C-96/35/90	MΩ	>10 ⁸

	Dk (RC50%)		2.5.5.9	1GHz;C-24/23/50	/	4.7
	Df (RC50%)		2.5.5.9	1GHz;C-24/23/50	/	0.020
物理性能 Physical	红光透过性 Red light permeability		/	Internal standard	%	0
	弯曲强度 Flexural Strength	LW	2.4.4	A	MPa	590
		CW				520
	弯曲模量 Flexural modulus		JB/T 6544-1993	A	GPa	29
	杨氏模量 Young's Modulus		GB/T 22315-2008	A	GPa	28
	剥离强度 Peel Strength (Hoz Copper Foil)		2.4.8	288°C/10s	lb/inch	5.0
	热导率 Thermal conductivity		ASTM-D5470	C-96/35/90	W/(m*k)	0.78
吸水率 Moisture Absorption		2.6.2.1	D-24/23	%	0.09	

Specimen thickness: 0.4mm or 0.8mm. Test Method is according to IPC TM-650 or National Standard Test Method.